E·XFL

Intel - EP20K100EFC144-2N Datasheet



Welcome to <u>E-XFL.COM</u>

Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	416
Number of Logic Elements/Cells	4160
Total RAM Bits	53248
Number of I/O	93
Number of Gates	263000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	144-BGA
Supplier Device Package	144-FBGA (13x13)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep20k100efc144-2n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

- Flexible clock management circuitry with up to four phase-locked loops (PLLs)
 - Built-in low-skew clock tree
 - Up to eight global clock signals
 - ClockLock[®] feature reducing clock delay and skew
 - ClockBoost[®] feature providing clock multiplication and division
 - ClockShiftTM programmable clock phase and delay shifting
- Powerful I/O features
 - Compliant with peripheral component interconnect Special Interest Group (PCI SIG) PCI Local Bus Specification, Revision 2.2 for 3.3-V operation at 33 or 66 MHz and 32 or 64 bits
 - Support for high-speed external memories, including DDR SDRAM and ZBT SRAM (ZBT is a trademark of Integrated Device Technology, Inc.)
 - Bidirectional I/O performance $(t_{CO} + t_{SU})$ up to 250 MHz
 - LVDS performance up to 840 Mbits per channel
 - Direct connection from I/O pins to local interconnect providing fast t_{CO} and t_{SU} times for complex logic
 - MultiVolt I/O interface support to interface with 1.8-V, 2.5-V, 3.3-V, and 5.0-V devices (see Table 3)
 - Programmable clamp to V_{CCIO}
 - Individual tri-state output enable control for each pin
 - Programmable output slew-rate control to reduce switching noise
 - Support for advanced I/O standards, including low-voltage differential signaling (LVDS), LVPECL, PCI-X, AGP, CTT, stubseries terminated logic (SSTL-3 and SSTL-2), Gunning transceiver logic plus (GTL+), and high-speed terminated logic (HSTL Class I)
 - Pull-up on I/O pins before and during configuration
- Advanced interconnect structure
 - Four-level hierarchical FastTrack[®] Interconnect structure providing fast, predictable interconnect delays
 - Dedicated carry chain that implements arithmetic functions such as fast adders, counters, and comparators (automatically used by software tools and megafunctions)
 - Dedicated cascade chain that implements high-speed, high-fan-in logic functions (automatically used by software tools and megafunctions)
 - Interleaved local interconnect allows one LE to drive 29 other LEs through the fast local interconnect
- Advanced packaging options
 - Available in a variety of packages with 144 to 1,020 pins (see Tables 4 through 7)
 - FineLine BGA[®] packages maximize board space efficiency
- Advanced software support
 - Software design support and automatic place-and-route provided by the Altera[®] Quartus[®] II development system for

All APEX 20K devices are reconfigurable and are 100% tested prior to shipment. As a result, test vectors do not have to be generated for fault coverage purposes. Instead, the designer can focus on simulation and design verification. In addition, the designer does not need to manage inventories of different application-specific integrated circuit (ASIC) designs; APEX 20K devices can be configured on the board for the specific functionality required.

APEX 20K devices are configured at system power-up with data stored in an Altera serial configuration device or provided by a system controller. Altera offers in-system programmability (ISP)-capable EPC1, EPC2, and EPC16 configuration devices, which configure APEX 20K devices via a serial data stream. Moreover, APEX 20K devices contain an optimized interface that permits microprocessors to configure APEX 20K devices serially or in parallel, and synchronously or asynchronously. The interface also enables microprocessors to treat APEX 20K devices as memory and configure the device by writing to a virtual memory location, making reconfiguration easy.

After an APEX 20K device has been configured, it can be reconfigured in-circuit by resetting the device and loading new data. Real-time changes can be made during system operation, enabling innovative reconfigurable computing applications.

APEX 20K devices are supported by the Altera Quartus II development system, a single, integrated package that offers HDL and schematic design entry, compilation and logic synthesis, full simulation and worst-case timing analysis, SignalTap logic analysis, and device configuration. The Quartus II software runs on Windows-based PCs, Sun SPARCstations, and HP 9000 Series 700/800 workstations.

The Quartus II software provides NativeLink interfaces to other industrystandard PC- and UNIX workstation-based EDA tools. For example, designers can invoke the Quartus II software from within third-party design tools. Further, the Quartus II software contains built-in optimized synthesis libraries; synthesis tools can use these libraries to optimize designs for APEX 20K devices. For example, the Synopsys Design Compiler library, supplied with the Quartus II development system, includes DesignWare functions optimized for the APEX 20K architecture.

Functional Description

APEX 20K devices incorporate LUT-based logic, product-term-based logic, and memory into one device. Signal interconnections within APEX 20K devices (as well as to and from device pins) are provided by the FastTrack[®] Interconnect—a series of fast, continuous row and column channels that run the entire length and width of the device.

Each I/O pin is fed by an I/O element (IOE) located at the end of each row and column of the FastTrack Interconnect. Each IOE contains a bidirectional I/O buffer and a register that can be used as either an input or output register to feed input, output, or bidirectional signals. When used with a dedicated clock pin, these registers provide exceptional performance. IOEs provide a variety of features, such as 3.3-V, 64-bit, 66-MHz PCI compliance; JTAG BST support; slew-rate control; and tri-state buffers. APEX 20KE devices offer enhanced I/O support, including support for 1.8-V I/O, 2.5-V I/O, LVCMOS, LVTTL, LVPECL, 3.3-V PCI, PCI-X, LVDS, GTL+, SSTL-2, SSTL-3, HSTL, CTT, and 3.3-V AGP I/O standards.

The ESB can implement a variety of memory functions, including CAM, RAM, dual-port RAM, ROM, and FIFO functions. Embedding the memory directly into the die improves performance and reduces die area compared to distributed-RAM implementations. Moreover, the abundance of cascadable ESBs ensures that the APEX 20K device can implement multiple wide memory blocks for high-density designs. The ESB's high speed ensures it can implement small memory blocks without any speed penalty. The abundance of ESBs ensures that designers can create as many different-sized memory blocks as the system requires. Figure 1 shows an overview of the APEX 20K device.



Cascade Chain

With the cascade chain, the APEX 20K architecture can implement functions with a very wide fan-in. Adjacent LUTs can compute portions of a function in parallel; the cascade chain serially connects the intermediate values. The cascade chain can use a logical AND or logical OR (via De Morgan's inversion) to connect the outputs of adjacent LEs. Each additional LE provides four more inputs to the effective width of a function, with a short cascade delay. Cascade chain logic can be created automatically by the Quartus II software Compiler during design processing, or manually by the designer during design entry.

Cascade chains longer than ten LEs are implemented automatically by linking LABs together. For enhanced fitting, a long cascade chain skips alternate LABs in a MegaLAB structure. A cascade chain longer than one LAB skips either from an even-numbered LAB to the next even-numbered LAB, or from an odd-numbered LAB to the next odd-numbered LAB. For example, the last LE of the first LAB in the upper-left MegaLAB structure carries to the first LE of the third LAB in the MegaLAB structure. Figure 7 shows how the cascade function can connect adjacent LEs to form functions with a wide fan-in.



Figure 7. APEX 20K Cascade Chain

Read/Write Clock Mode

The read/write clock mode contains two clocks. One clock controls all registers associated with writing: data input, WE, and write address. The other clock controls all registers associated with reading: read enable (RE), read address, and data output. The ESB also supports clock enable and asynchronous clear signals; these signals also control the read and write registers independently. Read/write clock mode is commonly used for applications where reads and writes occur at different system frequencies. Figure 20 shows the ESB in read/write clock mode.



Notes to Figure 20:

- (1) All registers can be cleared asynchronously by ESB local interconnect signals, global signals, or the chip-wide reset.
- (2) APEX 20KE devices have four dedicated clocks.

Table 10 describes the APEX 20K programmable delays and their logic options in the Quartus II software.

Table 10. APEX 20K Programmable Delay Chains							
Programmable Delays	Quartus II Logic Option						
Input pin to core delay	Decrease input delay to internal cells						
Input pin to input register delay	Decrease input delay to input register						
Core to output register delay	Decrease input delay to output register						
Output register t_{CO} delay	Increase delay to output pin						

The Quartus II software compiler can program these delays automatically to minimize setup time while providing a zero hold time. Figure 25 shows how fast bidirectional I/Os are implemented in APEX 20K devices.

The register in the APEX 20K IOE can be programmed to power-up high or low after configuration is complete. If it is programmed to power-up low, an asynchronous clear can control the register. If it is programmed to power-up high, the register cannot be asynchronously cleared or preset. This feature is useful for cases where the APEX 20K device controls an active-low input or another device; it prevents inadvertent activation of the input upon power-up.

Advanced I/O Standard Support

APEX 20KE IOEs support the following I/O standards: LVTTL, LVCMOS, 1.8-V I/O, 2.5-V I/O, 3.3-V PCI, PCI-X, 3.3-V AGP, LVDS, LVPECL, GTL+, CTT, HSTL Class I, SSTL-3 Class I and II, and SSTL-2 Class I and II.



For more information on I/O standards supported by APEX 20KE devices, see *Application Note* 117 (*Using Selectable I/O Standards in Altera Devices*).

The APEX 20KE device contains eight I/O banks. In QFP packages, the banks are linked to form four I/O banks. The I/O banks directly support all standards except LVDS and LVPECL. All I/O banks can support LVDS and LVPECL with the addition of external resistors. In addition, one block within a bank contains circuitry to support high-speed True-LVDS and LVPECL inputs, and another block within a particular bank supports high-speed True-LVDS and LVPECL outputs. The LVDS blocks support all of the I/O standards. Each I/O bank has its own VCCIO pins. A single device can support 1.8-V, 2.5-V, and 3.3-V interfaces; each bank can support a different standard independently. Each bank can also use a separate V_{REF} level so that each bank can support any of the terminated standards (such as SSTL-3) independently. Within a bank, any one of the terminated standards can be supported. EP20K300E and larger APEX 20KE devices support the LVDS interface for data pins (smaller devices support LVDS clock pins, but not data pins). All EP20K300E and larger devices support the LVDS interface for data pins up to 155 Mbit per channel; EP20K400E devices and larger with an X-suffix on the ordering code add a serializer/deserializer circuit and PLL for higher-speed support.

Each bank can support multiple standards with the same VCCIO for output pins. Each bank can support one voltage-referenced I/O standard, but it can support multiple I/O standards with the same VCCIO voltage level. For example, when VCCIO is 3.3 V, a bank can support LVTTL, LVCMOS, 3.3-V PCI, and SSTL-3 for inputs and outputs.

When the LVDS banks are not used as LVDS I/O banks, they support all of the other I/O standards. Figure 29 shows the arrangement of the APEX 20KE I/O banks.



Figure 29. APEX 20KE I/O Banks

Notes to Figure 29:

- For more information on placing I/O pins in LVDS blocks, refer to the Guidelines for Using LVDS Blocks section in Application Note 120 (Using LVDS in APEX 20KE Devices).
- (2) If the LVDS input and output blocks are not used for LVDS, they can support all of the I/O standards and can be used as input, output, or bidirectional pins with V_{CCIO} set to 3.3 V, 2.5 V, or 1.8 V.

Power Sequencing & Hot Socketing

Because APEX 20K and APEX 20KE devices can be used in a mixedvoltage environment, they have been designed specifically to tolerate any possible power-up sequence. Therefore, the V_{CCIO} and V_{CCINT} power supplies may be powered in any order.

For more information, please refer to the "Power Sequencing Considerations" section in the *Configuring APEX 20KE & APEX 20KC Devices* chapter of the *Configuration Devices Handbook*.

Signals can be driven into APEX 20K devices before and during power-up without damaging the device. In addition, APEX 20K devices do not drive out during power-up. Once operating conditions are reached and the device is configured, APEX 20K and APEX 20KE devices operate as specified by the user.

APEX 20KE devices also support the MultiVolt I/O interface feature. The APEX 20KE VCCINT pins must always be connected to a 1.8-V power supply. With a 1.8-V V_{CCINT} level, input pins are 1.8-V, 2.5-V, and 3.3-V tolerant. The VCCIO pins can be connected to either a 1.8-V, 2.5-V, or 3.3-V power supply, depending on the I/O standard requirements. When the VCCIO pins are connected to a 1.8-V power supply, the output levels are compatible with 1.8-V systems. When VCCIO pins are connected to a 2.5-V power supply, the output levels are compatible with 2.5-V systems. When VCCIO pins are connected to a 3.3-V power supply, the output levels are sometime with 2.5-V systems. When VCCIO pins are connected to a 3.3-V power supply, the output high is 3.3 V and compatible with 3.3-V or 5.0-V systems. An APEX 20KE device is 5.0-V tolerant with the addition of a resistor.

Table 13 summarizes APEX 20KE MultiVolt I/O support.

Table 13. /	Table 13. APEX 20KE MultiVolt I/O Support Note (1)												
V _{CCIO} (V)		Input Siç	jnals (V)			Output S	ignals (V)						
	1.8	2.5	3.3	5.0	1.8	2.5	3.3	5.0					
1.8	\checkmark	\checkmark	\checkmark		\checkmark								
2.5	\checkmark	\checkmark	>			\checkmark							
3.3	\checkmark	\checkmark	\checkmark	(2)			✓(3)						

Notes to Table 13:

 The PCI clamping diode must be disabled to drive an input with voltages higher than V_{CCIO}, except for the 5.0-V input case.

(2) An APEX 20KE device can be made 5.0-V tolerant with the addition of an external resistor. You also need a PCI clamp and series resistor.

(3) When V_{CCIO} = 3.3 V, an APEX 20KE device can drive a 2.5-V device with 3.3-V tolerant inputs.

ClockLock & ClockBoost Features

APEX 20K devices support the ClockLock and ClockBoost clock management features, which are implemented with PLLs. The ClockLock circuitry uses a synchronizing PLL that reduces the clock delay and skew within a device. This reduction minimizes clock-to-output and setup times while maintaining zero hold times. The ClockBoost circuitry, which provides a clock multiplier, allows the designer to enhance device area efficiency by sharing resources within the device. The ClockBoost circuitry allows the designer to distribute a low-speed clock and multiply that clock on-device. APEX 20K devices include a high-speed clock tree; unlike ASICs, the user does not have to design and optimize the clock tree. The ClockLock and ClockBoost features work in conjunction with the APEX 20K device's high-speed clock to provide significant improvements in system performance and band-width. Devices with an X-suffix on the ordering code include the ClockLock circuit.

The ClockLock and ClockBoost features in APEX 20K devices are enabled through the Quartus II software. External devices are not required to use these features.

For designs that require both a multiplied and non-multiplied clock, the clock trace on the board can be connected to CLK2p. Table 14 shows the combinations supported by the ClockLock and ClockBoost circuitry. The CLK2p pin can feed both the ClockLock and ClockBoost circuitry in the APEX 20K device. However, when both circuits are used, the other clock pin (CLK1p) cannot be used.

Table 14. Multiplication Factor Combinations						
Clock 1	Clock 2					
×1	×1					
×1, ×2	×2					
×1, ×2, ×4	×4					

APEX 20KE ClockLock Feature

APEX 20KE devices include an enhanced ClockLock feature set. These devices include up to four PLLs, which can be used independently. Two PLLs are designed for either general-purpose use or LVDS use (on devices that support LVDS I/O pins). The remaining two PLLs are designed for general-purpose use. The EP20K200E and smaller devices have two PLLs; the EP20K300E and larger devices have four PLLs.

The following sections describe some of the features offered by the APEX 20KE PLLs.

External PLL Feedback

The ClockLock circuit's output can be driven off-chip to clock other devices in the system; further, the feedback loop of the PLL can be routed off-chip. This feature allows the designer to exercise fine control over the I/O interface between the APEX 20KE device and another high-speed device, such as SDRAM.

Clock Multiplication

The APEX 20KE ClockBoost circuit can multiply or divide clocks by a programmable number. The clock can be multiplied by $m/(n \times k)$ or $m/(n \times v)$, where *m* and *k* range from 2 to 160, and *n* and *v* range from 1 to 16. Clock multiplication and division can be used for time-domain multiplexing and other functions, which can reduce design LE requirements.

Table 18. /	Table 18. APEX 20KE Clock Input & Output Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	I/O Standard	-1X Spe	-1X Speed Grade		-2X Speed Grade						
			Min	Max	Min	Max						
f _{IN}	Input clock frequency	3.3-V LVTTL	1.5	290	1.5	257	MHz					
		2.5-V LVTTL	1.5	281	1.5	250	MHz					
		1.8-V LVTTL	1.5	272	1.5	243	MHz					
		GTL+	1.5	303	1.5	261	MHz					
		SSTL-2 Class I	1.5	291	1.5	253	MHz					
		SSTL-2 Class II	1.5	291	1.5	253	MHz					
		SSTL-3 Class I	1.5	300	1.5	260	MHz					
		SSTL-3 Class II	1.5	300	1.5	260	MHz					
		LVDS	1.5	420	1.5	350	MHz					

Notes to Tables 17 and 18:

 All input clock specifications must be met. The PLL may not lock onto an incoming clock if the clock specifications are not met, creating an erroneous clock within the device.

- (2) The maximum lock time is 40 µs or 2000 input clock cycles, whichever occurs first.
- (3) Before configuration, the PLL circuits are disable and powered down. During configuration, the PLLs are still disabled. The PLLs begin to lock once the device is in the user mode. If the clock enable feature is used, lock begins once the CLKLK_ENA pin goes high in user mode.
- (4) The PLL VCO operating range is 200 MHz ð f_{VCO} ð 840 MHz for LVDS mode.

SignalTap Embedded Logic Analyzer

APEX 20K devices include device enhancements to support the SignalTap embedded logic analyzer. By including this circuitry, the APEX 20K device provides the ability to monitor design operation over a period of time through the IEEE Std. 1149.1 (JTAG) circuitry; a designer can analyze internal logic at speed without bringing internal signals to the I/O pins. This feature is particularly important for advanced packages such as FineLine BGA packages because adding a connection to a pin during the debugging process can be difficult after a board is designed and manufactured. The APEX 20K device instruction register length is 10 bits. The APEX 20K device USERCODE register length is 32 bits. Tables 20 and 21 show the boundary-scan register length and device IDCODE information for APEX 20K devices.

Table 20. APEX 20K Boundary-Scan Register Length								
Device	Boundary-Scan Register Length							
EP20K30E	420							
EP20K60E	624							
EP20K100	786							
EP20K100E	774							
EP20K160E	984							
EP20K200	1,176							
EP20K200E	1,164							
EP20K300E	1,266							
EP20K400	1,536							
EP20K400E	1,506							
EP20K600E	1,806							
EP20K1000E	2,190							
EP20K1500E	1 (1)							

Note to Table 20:

(1) This device does not support JTAG boundary scan testing.

Table 2	Table 25. APEX 20K 5.0-V Tolerant Device DC Operating Conditions (Part 2 of 2) Notes (2), (7), (8)											
Symbol	Parameter	Conditions	Min	Тур	Max	Unit						
V _{OL}	3.3-V low-level TTL output voltage	I _{OL} = 12 mA DC, V _{CCIO} = 3.00 V (11)			0.45	V						
	3.3-V low-level CMOS output voltage	I _{OL} = 0.1 mA DC, V _{CCIO} = 3.00 V (11)			0.2	V						
	3.3-V low-level PCI output voltage	$I_{OL} = 1.5 \text{ mA DC},$ $V_{CCIO} = 3.00 \text{ to } 3.60 \text{ V}$ (11)			$0.1 \times V_{CCIO}$	V						
	2.5-V low-level output voltage	I _{OL} = 0.1 mA DC, V _{CCIO} = 2.30 V (11)			0.2	V						
		I _{OL} = 1 mA DC, V _{CCIO} = 2.30 V (11)			0.4	V						
		I _{OL} = 2 mA DC, V _{CCIO} = 2.30 V (11)			0.7	V						
I _I	Input pin leakage current	$V_1 = 5.75$ to -0.5 V	-10		10	μA						
I _{OZ}	Tri-stated I/O pin leakage current	$V_{O} = 5.75$ to -0.5 V	-10		10	μA						
I _{CC0}	V _{CC} supply current (standby) (All ESBs in power-down mode)	V_1 = ground, no load, no toggling inputs, -1 speed grade (12)		10		mA						
		V ₁ = ground, no load, no toggling inputs, -2, -3 speed grades (12)		5		mA						
R _{CONF}	Value of I/O pin pull-up resistor	V _{CCIO} = 3.0 V (13)	20		50	W						
	before and during configuration	V _{CCIO} = 2.375 V (13)	30		80	W						



Figure 37. APEX 20KE f_{MAX} Timing Model

Tables 55 through 60 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K60E APEX 20KE devices.

Table 55. EP20K60E f _{MAX} LE Timing Microparameters										
Symbol		-1		-2		-3				
	Min	Max	Min	Max	Min	Max				
t _{SU}	0.17		0.15		0.16		ns			
t _H	0.32		0.33		0.39		ns			
t _{CO}		0.29		0.40		0.60	ns			
t _{LUT}		0.77		1.07		1.59	ns			

Table 69. EP20K160E f _{MAX} Routing Delays											
Symbol	ol -1		-2		-3		Unit				
	Min	Max	Min	Max	Min	Max					
t _{F1-4}		0.25		0.26		0.28	ns				
t _{F5-20}		1.00		1.18		1.35	ns				
t _{F20+}		1.95		2.19		2.30	ns				

Symbol	-	1	-2		-3	1	Unit
	Min	Max	Min	Max	Min	Max	1
t _{CH}	1.34		1.43		1.55		ns
t _{CL}	1.34		1.43		1.55		ns
t _{CLRP}	0.18		0.19		0.21		ns
t _{PREP}	0.18		0.19		0.21		ns
t _{ESBCH}	1.34		1.43		1.55		ns
t _{ESBCL}	1.34		1.43		1.55		ns
t _{ESBWP}	1.15		1.45		1.73		ns
t _{ESBRP}	0.93		1.15		1.38		ns

Table 71. EP20K160E External Timing Parameters											
Symbol	ol -1		-1 -2		-3	Unit					
	Min	Max	Min	Max	Min	Max					
t _{INSU}	2.23		2.34		2.47		ns				
t _{INH}	0.00		0.00		0.00		ns				
t _{outco}	2.00	5.07	2.00	5.59	2.00	6.13	ns				
t _{insupll}	2.12		2.07		-		ns				
t _{INHPLL}	0.00		0.00		-		ns				
t _{outcopll}	0.50	3.00	0.50	3.35	-	-	ns				

APEX 20K Programmable Logic Device Family Data Sheet

Table 99. EP20K1000E f _{MAX} Routing Delays										
Symbol	ymbol -1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit			
	Min	Max	Min	Max	Min	Max				
t _{F1-4}		0.27		0.27		0.27	ns			
t _{F5-20}		1.45		1.63		1.75	ns			
t _{F20+}		4.15		4.33		4.97	ns			

Table 100. EP20K1000E Minimum Pulse Width Timing Parameters										
Symbol	-1 Spee	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade				
	Min	Max	Min	Max	Min	Max				
t _{CH}	1.25		1.43		1.67		ns			
t _{CL}	1.25		1.43		1.67		ns			
t _{CLRP}	0.20		0.20		0.20		ns			
t _{PREP}	0.20		0.20		0.20		ns			
t _{ESBCH}	1.25		1.43		1.67		ns			
t _{ESBCL}	1.25		1.43		1.67		ns			
t _{ESBWP}	1.28		1.51		1.65		ns			
t _{ESBRP}	1.11		1.29		1.41		ns			

Table 101. EP20K1000E External Timing Parameters										
Symbol	-1 Speed Grade		-2 Spec	ed Grade	-3 Spee	d Grade	Unit			
	Min	Max	Min	Max	Min	Мах				
t _{INSU}	2.70		2.84		2.97		ns			
t _{INH}	0.00		0.00		0.00		ns			
t _{outco}	2.00	5.75	2.00	6.33	2.00	6.90	ns			
t _{INSUPLL}	1.64		2.09		-		ns			
t _{INHPLL}	0.00		0.00		-		ns			
t _{outcopll}	0.50	2.25	0.50	2.99	-	-	ns			

Table 102. EP20K1000E External Bidirectional Timing Parameters										
Symbol	-1 Speed Grade		-2 Spee	d Grade	-3 Spec	Unit				
	Min	Max	Min	Max	Min	Max				
t _{insubidir}	3.22		3.33		3.51		ns			
t _{inhbidir}	0.00		0.00		0.00		ns			
toutcobidir	2.00	5.75	2.00	6.33	2.00	6.90	ns			
t _{XZBIDIR}		6.31		7.09		7.76	ns			
t _{ZXBIDIR}		6.31		7.09		7.76	ns			
t _{INSUBIDIRPL} L	3.25		3.26				ns			
t _{inhbidirpll}	0.00		0.00				ns			
t _{outcobidirpll}	0.50	2.25	0.50	2.99			ns			
t _{XZBIDIRPLL}		2.81		3.80			ns			
t _{ZXBIDIRPLL}		2.81		3.80			ns			

Tables 103 through 108 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K1500E APEX 20KE devices.

Table 103. EP20K1500E f _{MAX} LE Timing Microparameters										
Symbol	Symbol -1 Speed Grad		-2 Spee	ed Grade	-3 Spee	Unit				
	Min	Max	Min	Max	Min	Max				
t _{SU}	0.25		0.25		0.25		ns			
t _H	0.25		0.25		0.25		ns			
t _{CO}		0.28		0.32		0.33	ns			
t _{LUT}		0.80		0.95		1.13	ns			

Т

Table 104. EP20K1500E f _{MAX} ESB Timing Microparameters										
Symbol	-1 Speed Grade		-2 Spe	-2 Speed Grade		d Grade	Unit			
	Min	Max	Min	Max	Min	Max				
t _{ESBARC}		1.78		2.02		1.95	ns			
t _{ESBSRC}		2.52		2.91		3.14	ns			
t _{ESBAWC}		3.52		4.11		4.40	ns			
t _{ESBSWC}		3.23		3.84		4.16	ns			
t _{ESBWASU}	0.62		0.67		0.61		ns			
t _{ESBWAH}	0.41		0.55		0.55		ns			
t _{ESBWDSU}	0.77		0.79		0.81		ns			
t _{ESBWDH}	0.41		0.55		0.55		ns			
t _{ESBRASU}	1.74		1.92		1.85		ns			
t _{ESBRAH}	0.00		0.01		0.23		ns			
t _{ESBWESU}	2.07		2.28		2.41		ns			
t _{ESBWEH}	0.00		0.00		0.00		ns			
t _{ESBDATASU}	0.25		0.27		0.29		ns			
t _{ESBDATAH}	0.13		0.13		0.13		ns			
t _{ESBWADDRSU}	0.11		0.04		0.11		ns			
t _{ESBRADDRSU}	0.14		0.11		0.16		ns			
t _{ESBDATACO1}		1.29		1.50		1.63	ns			
t _{ESBDATACO2}		2.55		2.99		3.22	ns			
t _{ESBDD}		3.12		3.57		3.85	ns			
t _{PD}		1.84		2.13		2.32	ns			
t _{PTERMSU}	1.08		1.19		1.32		ns			
t _{PTERMCO}		1.31		1.53		1.66	ns			

Table 105. EP20K1500E f _{MAX} Routing Delays									
Symbol	-1 Spe	ed Grade	-2 Spe	-2 Speed Grade -3		ed Grade	Unit		
	Min	Max	Min	Max	Min	Max			
t _{F1-4}		0.28		0.28		0.28	ns		
t _{F5-20}		1.36		1.50		1.62	ns		
t _{F20+}		4.43		4.48		5.07	ns		

Table 108. EP20K1500E External Bidirectional Timing Parameters										
Symbol	-1 Speed Grade		-2 Spee	d Grade	-3 Spee	Unit				
	Min	Max	Min	Max	Min	Max				
t _{insubidir}	3.47		3.68		3.99		ns			
t _{inhbidir}	0.00		0.00		0.00		ns			
toutcobidir	2.00	6.18	2.00	6.81	2.00	7.36	ns			
t _{XZBIDIR}		6.91		7.62		8.38	ns			
t _{ZXBIDIR}		6.91		7.62		8.38	ns			
t _{insubidirpll}	3.05		3.26				ns			
t _{inhbidirpll}	0.00		0.00				ns			
t _{outcobidirpll}	0.50	2.67	0.50	2.99			ns			
t _{XZBIDIRPLL}		3.41		3.80			ns			
t _{ZXBIDIRPLL}		3.41		3.80			ns			

Tables 109 and 110 show selectable I/O standard input and output delays for APEX 20KE devices. If you select an I/O standard input or output delay other than LVCMOS, add or subtract the selected speed grade to or from the LVCMOS value.

Table 109. Selectable I/O Standard Input Delays									
Symbol	-1 Spee	ed Grade	-2 Spec	ed Grade	d Grade -3 Spee		Unit		
	Min	Max	Min	Max	Min	Max	Min		
LVCMOS		0.00		0.00		0.00	ns		
LVTTL		0.00		0.00		0.00	ns		
2.5 V		0.00		0.04		0.05	ns		
1.8 V		-0.11		0.03		0.04	ns		
PCI		0.01		0.09		0.10	ns		
GTL+		-0.24		-0.23		-0.19	ns		
SSTL-3 Class I		-0.32		-0.21		-0.47	ns		
SSTL-3 Class II		-0.08		0.03		-0.23	ns		
SSTL-2 Class I		-0.17		-0.06		-0.32	ns		
SSTL-2 Class II		-0.16		-0.05		-0.31	ns		
LVDS		-0.12		-0.12		-0.12	ns		
CTT		0.00		0.00		0.00	ns		
AGP		0.00		0.00		0.00	ns		

Г